

Title (en)
METHOD OF TRANSFERRING A MICRO DEVICE

Title (de)
VERFAHREN ZUR ÜBERTRAGUNG EINER MIKROVORRICHTUNG

Title (fr)
PROCÉDÉ DE TRANSFERT D'UN MICRODISPOSITIF

Publication
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Application
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- US 201161561706 P 20111118
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- US 201213372292 A 20120213
- US 201213372310 A 20120213
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Abstract (en)
[origin: US8333860B1] A micro device transfer head and head array are disclosed. In an embodiment, the micro device transfer head includes a base substrate, a mesa structure with sidewalls, an electrode formed over the mesa structure, and a dielectric layer covering the electrode. A voltage can be applied to the micro device transfer head and head array to pick up a micro device from a carrier substrate and release the micro device onto a receiving substrate.

IPC 8 full level
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C-Set (source: EP US)
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3. **H01L 2924/1461 + H01L 2924/00**

Citation (search report)

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- [YA] US 2011151602 A1 20110623 - SPEIER INGO [CA]
- [YA] US 2005232728 A1 20051020 - RICE MICHAEL R [US], et al
- See references of WO 2013074357A1

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